



PORT PLASTICS

Semiconductor



Minimize Your Wet Process Waste **TECAFLON PVDF LARGE TUBES**

Several wet process steps are required in the production of an IC chip from a wafer. ECD, PECVD, ALD and Wafer Clean are examples of such process tools. Given the miniaturization of the chip combined with the higher throughput of wafers in the fab, fluoropolymers are often used in the manufacturing of the parts in the chamber and in wafer mobility applications. Fluoropolymers are known for chemical resistance and ionic purity but often not known for mechanical performance. In the unique case of PVDF, while sacrificing a bit of chemical resistance to PTFE especially with respect to extremely strong acids, the tensile strength however can be as much as 40% higher than PTFE yielding a robust part. Given that silicon wafers are round many of the parts are donut shaped allowing for the wafer to pass thru the part. Of course, machining these parts from a rectangular shape is inefficient and produces a high volume of waste, often in excess of 80%!

Ensinger has developed and offers large scale TECAFLON PVDF tube available in three sizes that can dramatically reduce your waste reducing overall costs.

18.5" OD x 16" ID x 36" L (470mm x 406mm x 914mm)

16" OD x 14" ID x 36" L (406mm x 356mm x 914mm)

14" OD x 12.5 ID x 36" L (356mm x 318mm x 914mm)

**TO LEARN MORE ABOUT HOW TECAFLON PVDF TUBE CAN BRING VALUE TO YOUR APPLICATION,
CONTACT YOUR LOCAL PORT PLASTICS PROFESSIONAL. PORTPLASTICS.COM**

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